



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-12-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	LDO7*0912AAW	A	BO2A	2013-12-12
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LDO7*0912AAW					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.366	mg	supplier	die	Silicon (Si)	7440-21-3		3.308	mg	982769	41350
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	8021	338
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.014	mg	4159	175
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	5051	213
Leadframe	Copper & its alloys	34.343	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.062	mg	991818	425775
				supplier	alloy	Iron (Fe)	7439-89-6		0.016	mg	466	200
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.029	mg	844	363
				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	6872	2950
Die attach	Other Organic Materials	1.042	mg	supplier	glue	Silver (Ag)	7440-22-4		0.948	mg	909789	11850
				supplier	glue	acrylate	Proprietary		0.052	mg	49904	650
				supplier	glue	Methacrylate	Proprietary		0.042	mg	40307	525
Bonding wire	Other inorganic materials	0.054	mg	supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	675
encapsulation	Other Organic Materials	40.166	mg	supplier	mold compound	Silica, vitreous	60676-86-0		35.225	mg	876986	440313
				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.607	mg	40009	20088
				supplier	mold compound	Epoxy resin B	29690-82-2		1.607	mg	40009	20088
				supplier	mold compound	phenol resin	Proprietary		1.205	mg	30000	15063
				supplier	mold compound	carbon black	1333-86-4		0.12	mg	2988	1500
				supplier	mold compound	additive	Proprietary		0.402	mg	10008	5025
connections coating	Solder	1.029	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.029	mg	1000000	12863